

**Electrical Characteristics at  $T_A = 25^\circ\text{C}$ , unless otherwise specified**

Parameter	Symbol	Values			Unit
		min.	typ.	max.	
DC Characteristics					
Reverse current $V_R = 16\text{ V}$ $V_R = 16\text{ V}, T_A = 65\text{ }^{\circ}\text{C}$	$I_R$	- -	- -	20 200	nA
AC Characteristics					
Diode capacitance <sup>1)</sup> $V_R = 2\text{ V}, f = 1\text{ MHz}$	$C_T$	42	-	47.5	pF
Capacitance ratio $V_R = 2\text{ V}, V_R = 8\text{ V}, f = 1\text{ MHz}$	$C_{T2}/C_{T8}$	1.65	1.71	-	
Series resistance $V_R = 2\text{ V}, f = 100\text{ MHz}$	$r_S$	-	0.18	-	$\Omega$
Figure of merit $f = 100\text{ MHz}, V_R = 2\text{ V}$	$Q$	-	200	-	
Temperature coefficient of diode capacitance $V_R = 2\text{ V}, f = 1\text{ MHz}$	$TC_C$	-	330	-	ppm/K

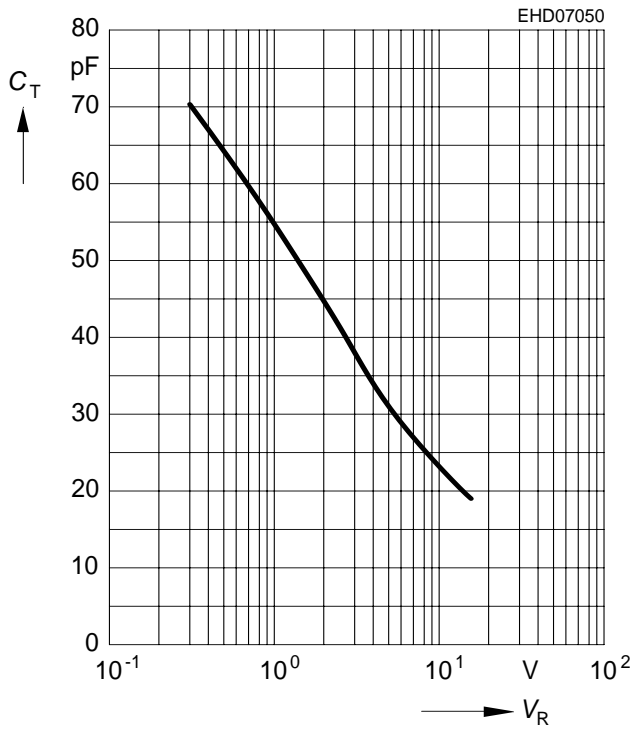
<sup>1</sup> Capacitance groups at 2V, coded 1; 2; 3

$C_T$ /groups	1	2	3
$C_{2V}$ min	43pF	44pF	45pF
$C_{2V}$ max	44.5pF	45.5pF	46.5pF

The capacitance subgroup is marked by the subgroup number printed on the component and the package label. A packing unit (e.g. 8mm tape) contain diodes of one subgroup only. Delivery of different capacitance subgroups requires a special agreement.

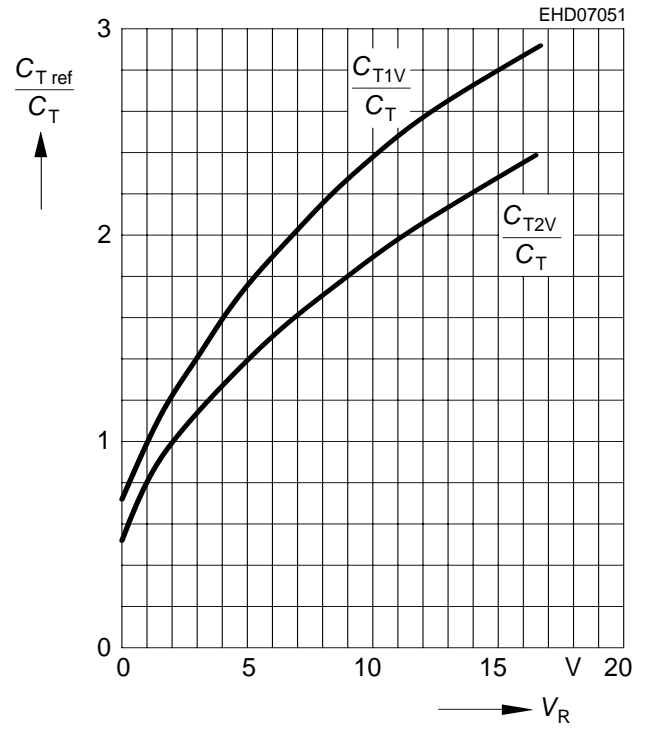
**Diode capacitance  $C_T = f(V_R)$**

$f = 1\text{MHz}$

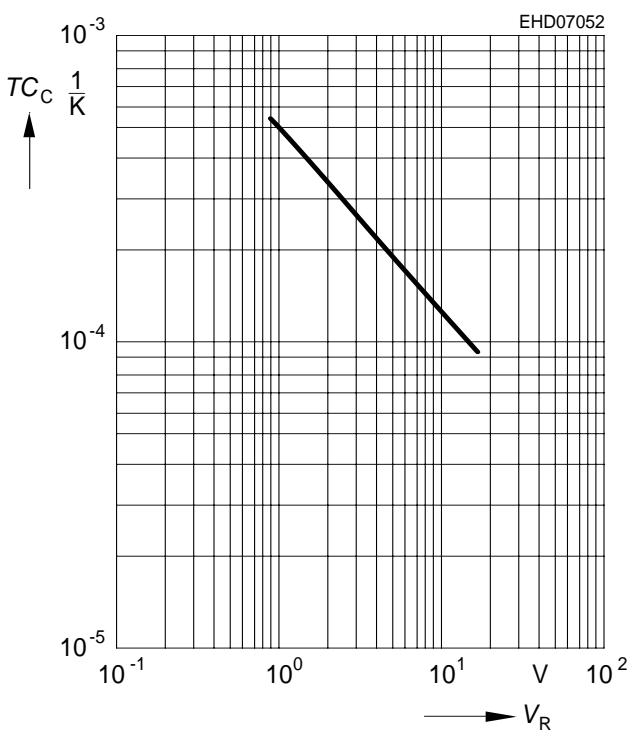


**Capacitance ratio  $C_{T\text{ref}}/C_T = f(V_R)$**

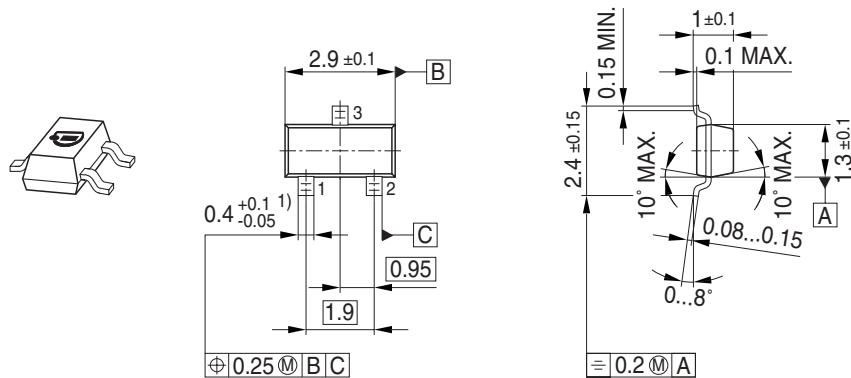
$f = 1\text{MHz}$



**Temperatur coefficient  $TC_C = f(V_R)$**

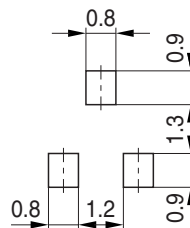


## Package Outline

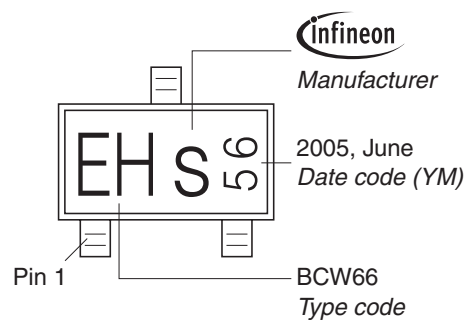


1) Lead width can be 0.6 max. in dambar area

## Foot Print

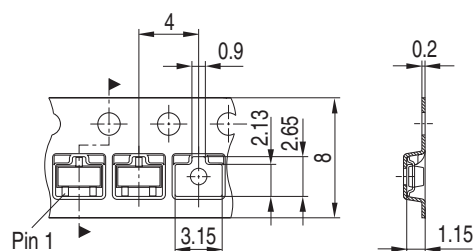


## Marking Layout (Example)



## Standard Packing

Reel ø180 mm = 3.000 Pieces/Reel  
Reel ø330 mm = 10.000 Pieces/Reel



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